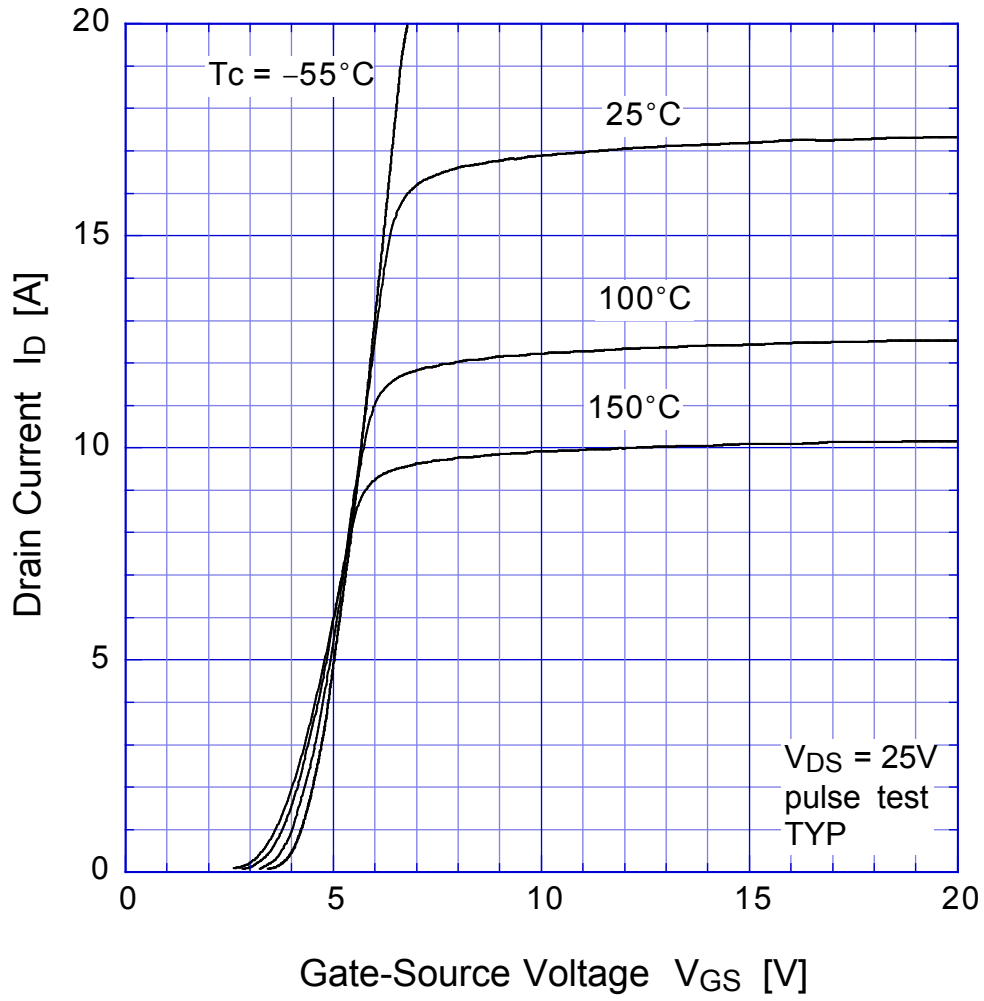


●Electrical Characteristics $T_c = 25^\circ\text{C}$

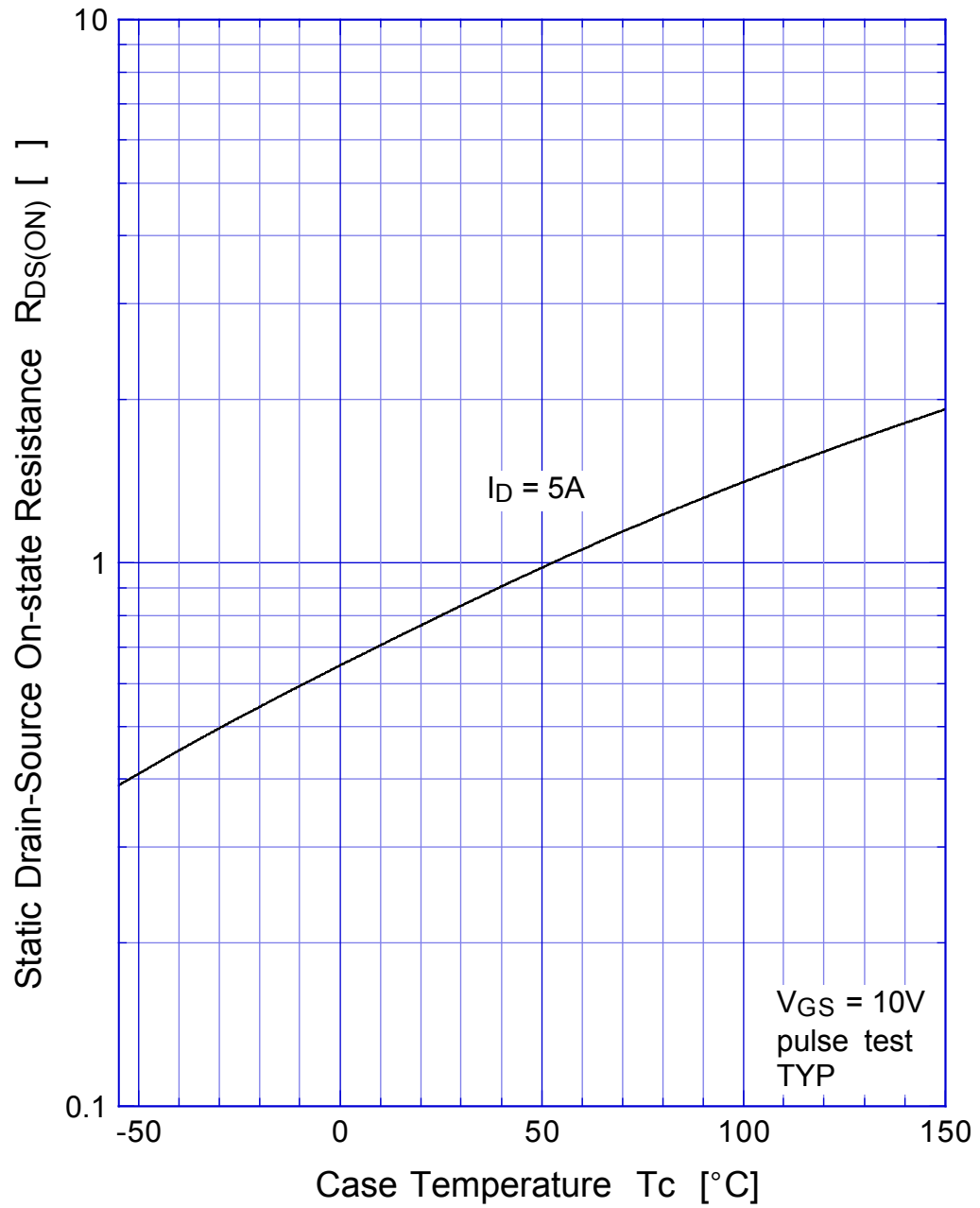
| Item | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|---------------|---|------|------|-----------|---------------------------|
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $I_D = 1\text{mA}, V_{GS} = 0\text{V}$ | 500 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 500\text{V}, V_{GS} = 0\text{V}$ | | | 250 | μA |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS} = \pm 30\text{V}, V_{DS} = 0\text{V}$ | | | ± 0.1 | |
| Forward Transconductance | g_{fs} | $I_D = 5\text{A}, V_{DS} = 10\text{V}$ | 2.4 | 6.3 | | S |
| Static Drain-Source On-state Resistance | $R_{DS(ON)}$ | $I_D = 5\text{A}, V_{GS} = 10\text{V}$ | | 0.8 | 1.0 | Ω |
| Gate Threshold Voltage | V_{TH} | $I_D = 1\text{mA}, V_{DS} = 10\text{V}$ | 2.5 | 3.0 | 3.5 | V |
| Source-Drain Diode Forward Voltage | V_{SD} | $I_S = 5\text{A}, V_{GS} = 0\text{V}$ | | | 1.5 | |
| Thermal Resistance | θ_{jc} | junction to case | | | 3.12 | $^\circ\text{C}/\text{W}$ |
| Total Gate Charge | Q_g | $V_{DD} = 400\text{V}, V_{GS} = 10\text{V}, I_D = 10\text{A}$ | | 30 | | nC |
| Input Capacitance | C_{iss} | $V_{DS} = 10\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ | | 890 | | pF |
| Reverse Transfer Capacitance | C_{rss} | | | 70 | | |
| Output Capacitance | C_{oss} | | | 200 | | |
| Turn-On Time | t_{on} | $I_D = 5\text{A}, V_{GS} = 10\text{V}, R_L = 30\Omega$ | | 70 | 110 | ns |
| Turn-Off Time | t_{off} | $V_{GS} = 0\text{V}$ | | 140 | 220 | |

2SK2188

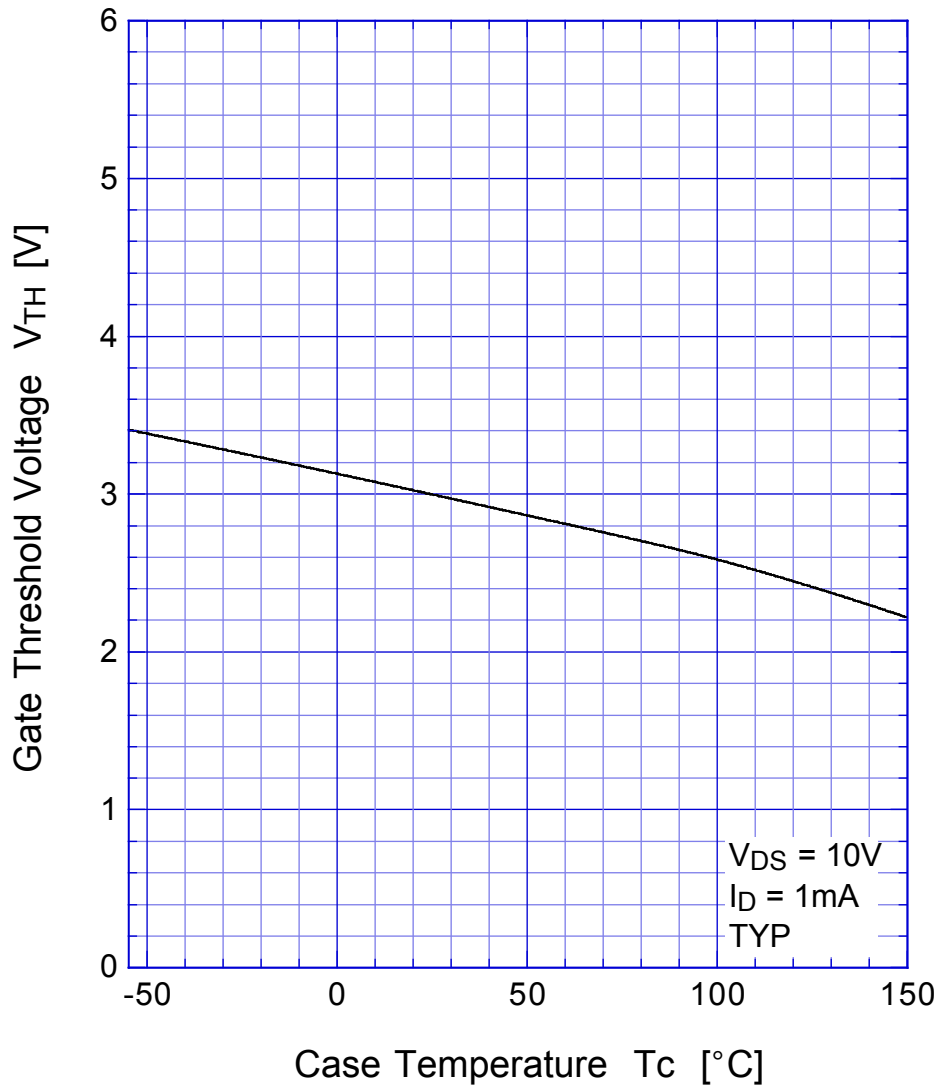
Transfer Characteristics



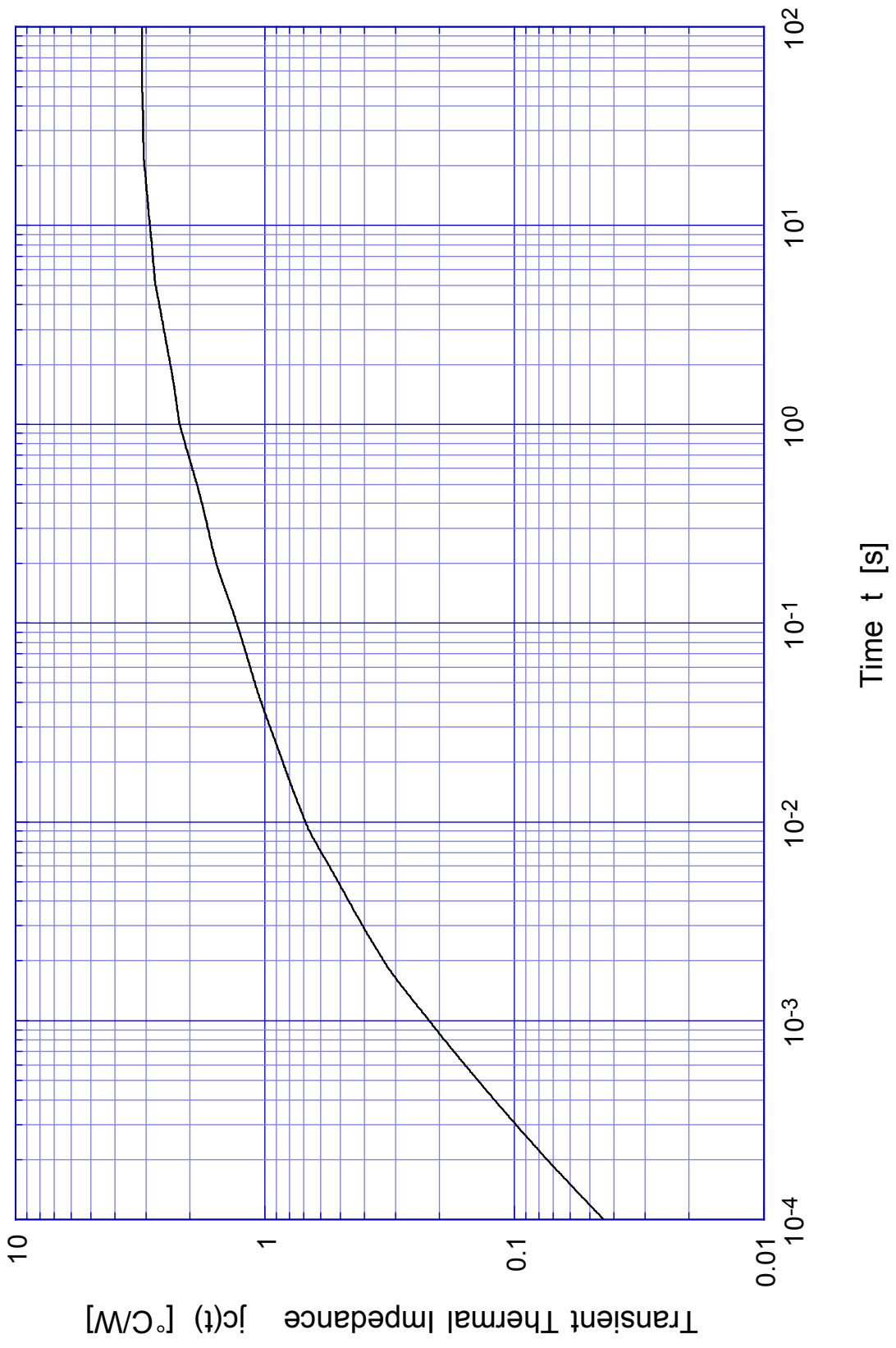
2SK2188 Static Drain-Source On-state Resistance



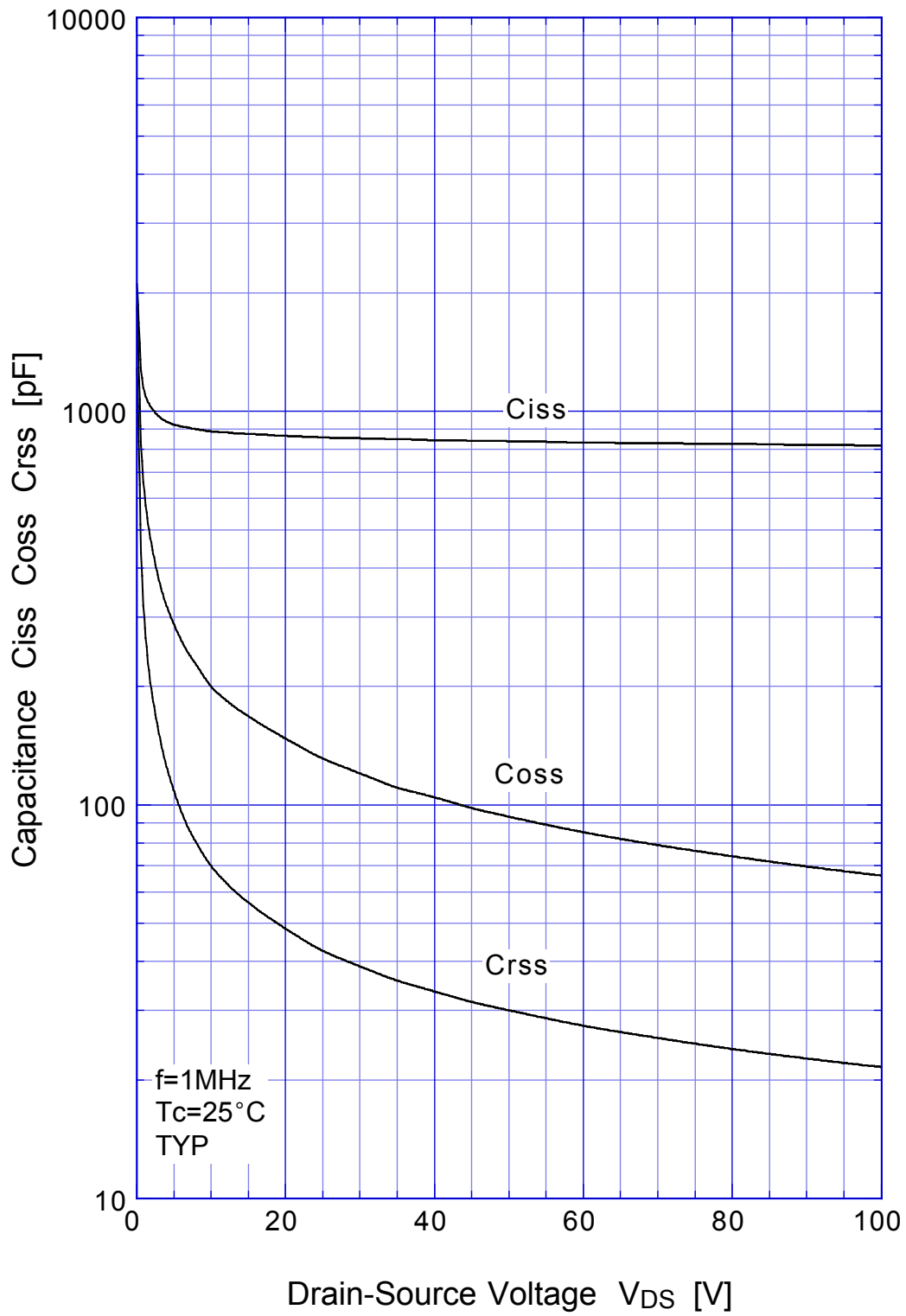
2SK2188 Gate Threshold Voltage



2SK2188 Transient Thermal Impedance



2SK2188 Capacitance



2SK2188

Power Derating



2SK2188 Gate Charge Characteristics

